

Description

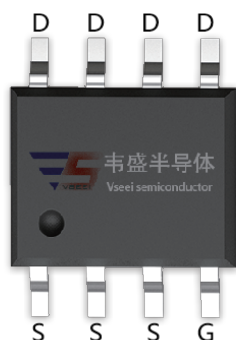
The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

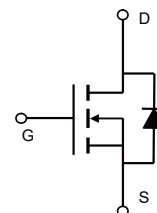
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- $V_{DS} = 120V, I_D = 11A$
 $R_{DS(ON)} = 13.3m\Omega$, typical@ $V_{GS} = 10V$
 $R_{DS(ON)} = 16.2m\Omega$, typical@ $V_{GS} = 4.5V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating



SOP-8



Schematic

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST12N130	VST12N130-S8	SOP-8	-	-	-

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	120	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	11	A
Drain Current-Continuous($T_C = 100^\circ\text{C}$)	$I_D(100^\circ\text{C})$	7.7	A
Pulsed Drain Current	I_{DM}	44	A
Maximum Power Dissipation	P_D	3.4	W
Single pulse avalanche energy (Note 4)	E_{AS}	200	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	37	$^\circ\text{C/W}$
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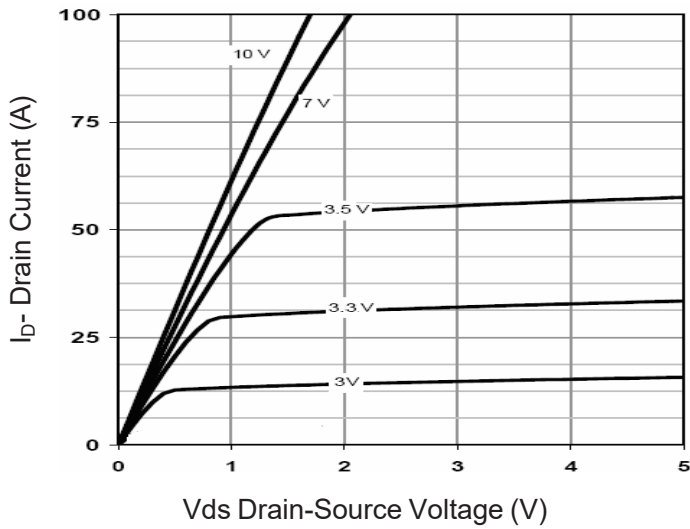
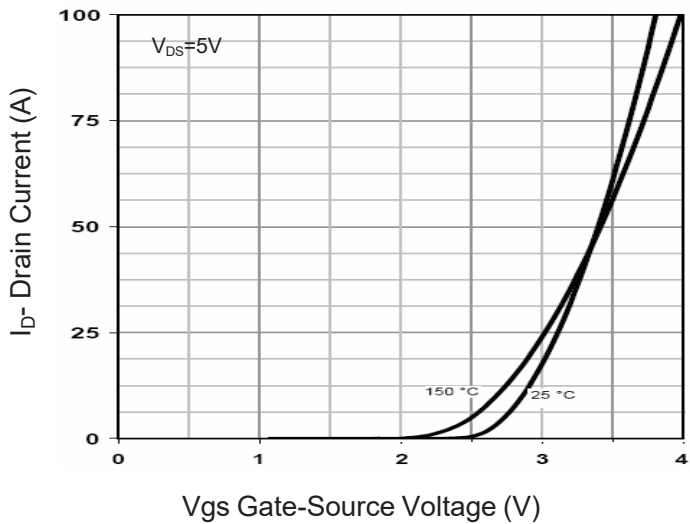
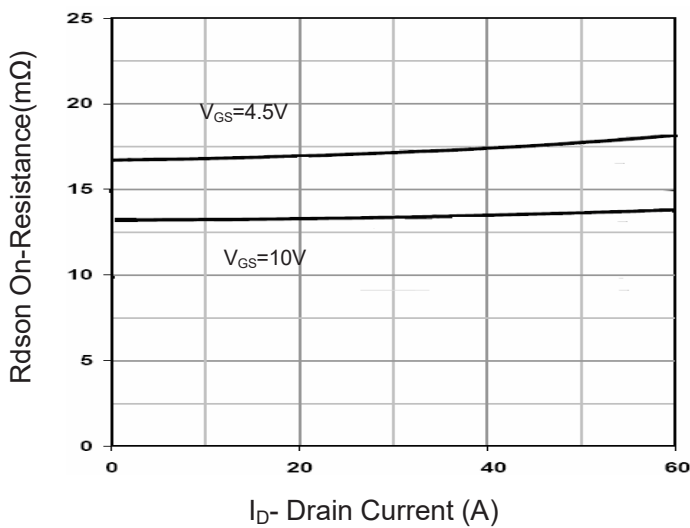
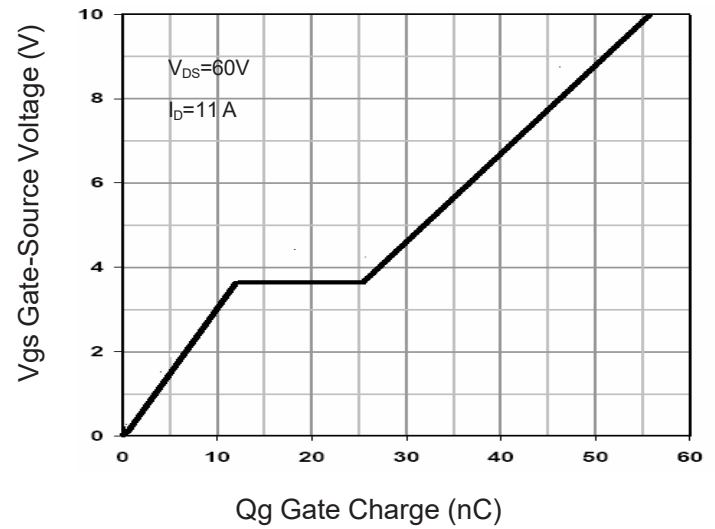
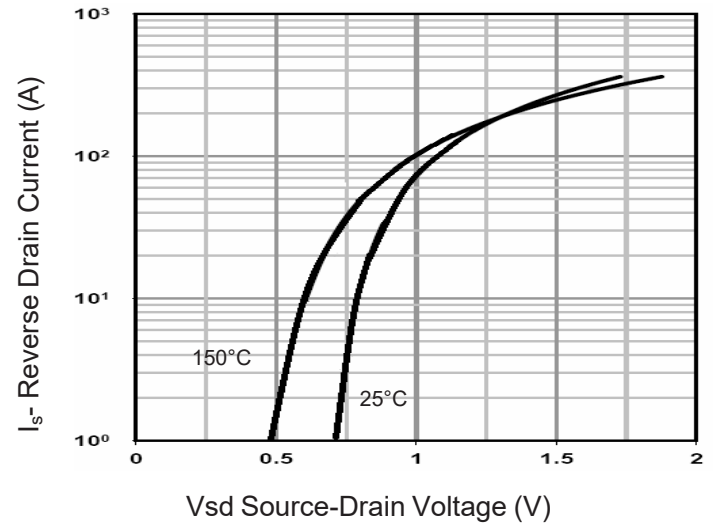
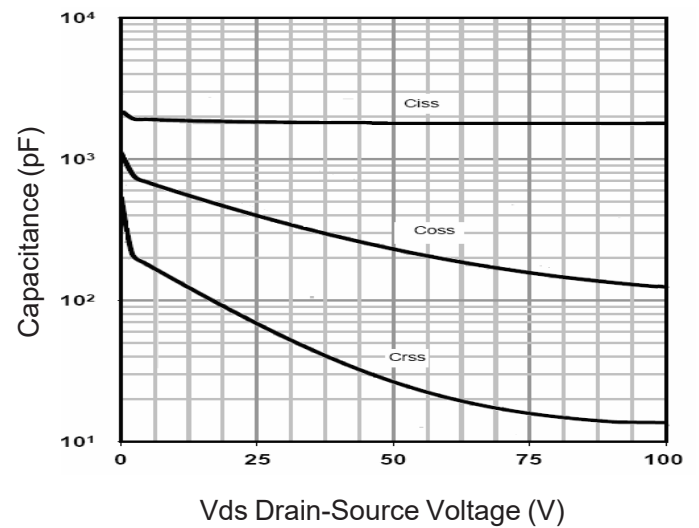
Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

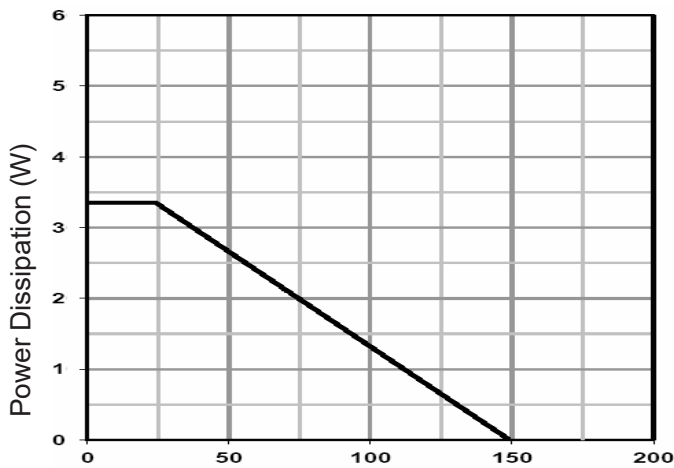
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	120		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =120V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.1	1.7	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =11A	-	13.3	14.0	mΩ
		V _{GS} =4.5V, I _D =11A	-	16.2	18.0	
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =11A		45	-	S
Dynamic Characteristics (Note3)						
Input Capacitance	C _{iss}	V _{DS} =60V,V _{GS} =0V, F=1.0MHz	-	2800	-	pF
Output Capacitance	C _{oss}		-	180	-	pF
Reverse Transfer Capacitance	C _{rss}		-	20	-	pF
Switching Characteristics (Note 3)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =60V,I _D =11A V _{GS} =10V,R _G =1.6Ω	-	13	-	nS
Turn-on Rise Time	t _r		-	10	-	nS
Turn-Off Delay Time	t _{d(off)}		-	30	-	nS
Turn-Off Fall Time	t _f		-	8	-	nS
Total Gate Charge	Q _g	V _{DS} =60V,I _D =11A, V _{GS} =10V	-	56	-	nC
Gate-Source Charge	Q _{gs}		-	12.5	-	nC
Gate-Drain Charge	Q _{gd}		-	14	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 2)	V _{SD}	V _{GS} =0V,I _S =11A	-	-	1.2	V
Diode Forward Current	I _S		-	-	11	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 11A di/dt = 100A/μs ^(Note3)	-	55	-	nS
Reverse Recovery Charge	Q _{rr}		-	98	-	nC

Notes:

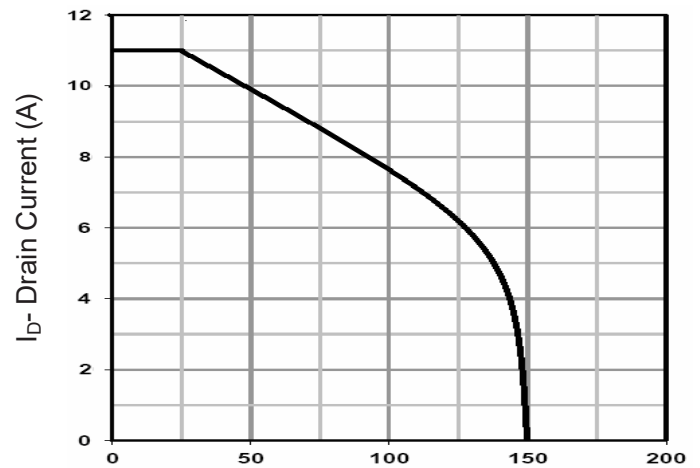
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
3. Guaranteed by design, not subject to production
4. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, L=0.25mH, R_g=25\Omega$

Typical Electrical and Thermal Characteristics

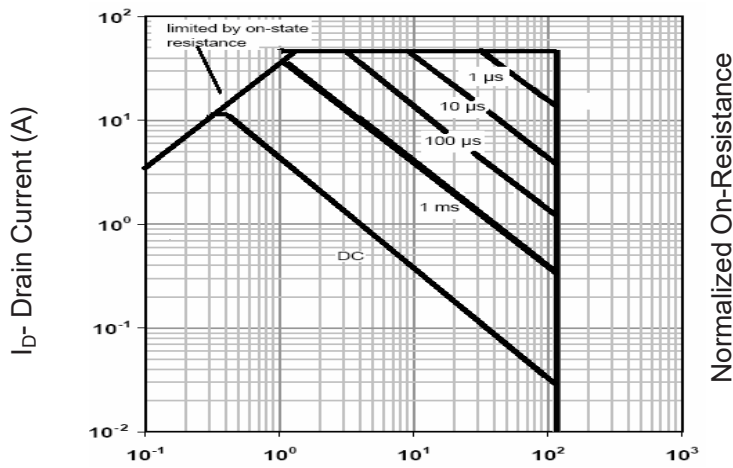

Figure 1 Output Characteristics

Figure 2 Transfer Characteristics

Figure 3 Rdson- Drain Current

Figure 4 Gate Charge

Figure 5 Source- Drain Diode Forward

Figure 6 Capacitance vs Vds



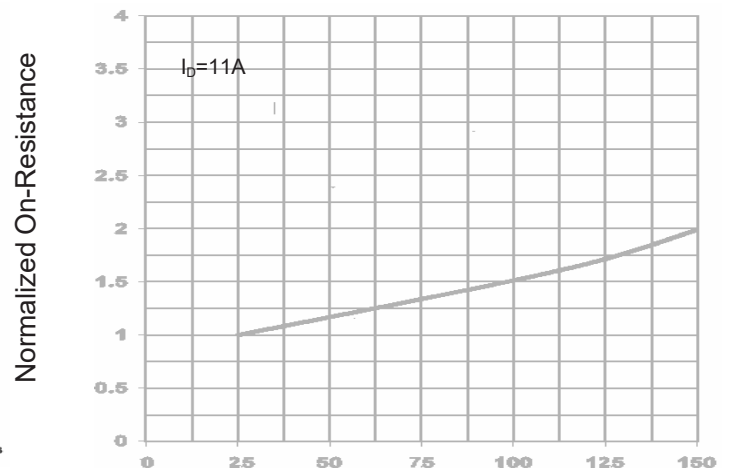
T_J -Junction Temperature(°C)
Figure 7 Power De-rating



T_J -Junction Temperature (°C)
Figure 9 Current De-rating



V_{ds} Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T_J -Junction Temperature(°C)
Figure 10 Rdson-Junction Temperature

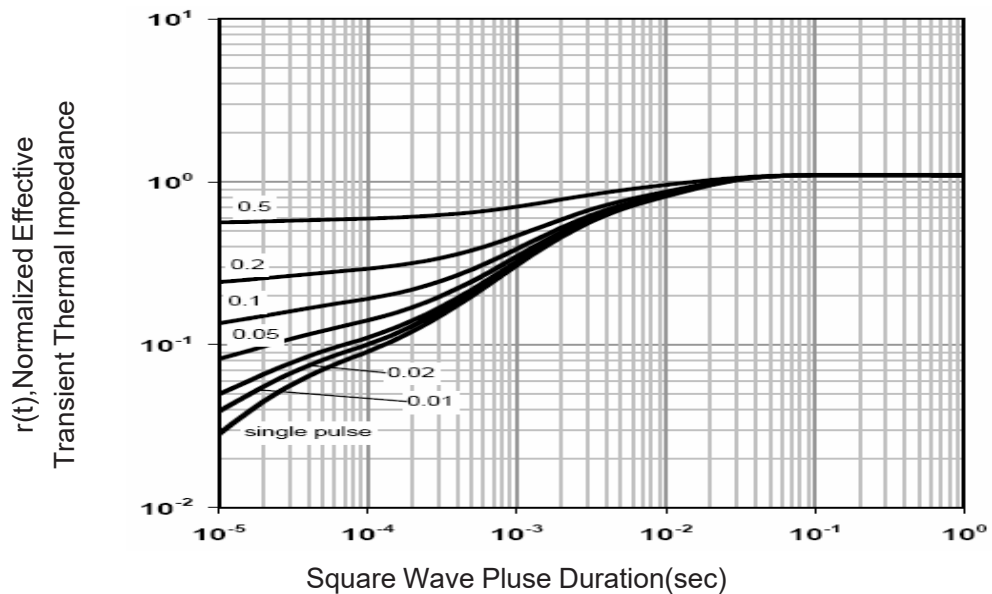


Figure 11 Normalized Maximum Transient Thermal Impedance